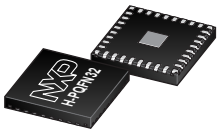
SOT2224-1(SC)

H-PQFN32, thermal enhanced - plastic quad flat non-lead, 32 terminals, 0.5 mm pitch, 5 mm x 5 mm x 0.75 mm body

15 July 2026 Package information



1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	H-PQFN32
Package style descriptive code	H-PQFN (thermal enhanced - plastic quad flat non-lead)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	30-10-2024
Manufacturer package code	98ASA02122

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	4.9	5	5.1	mm
package width	4.9	5	5.1	mm
seated height	0.7	0.75	0.8	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	32	-	

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2 Package outline

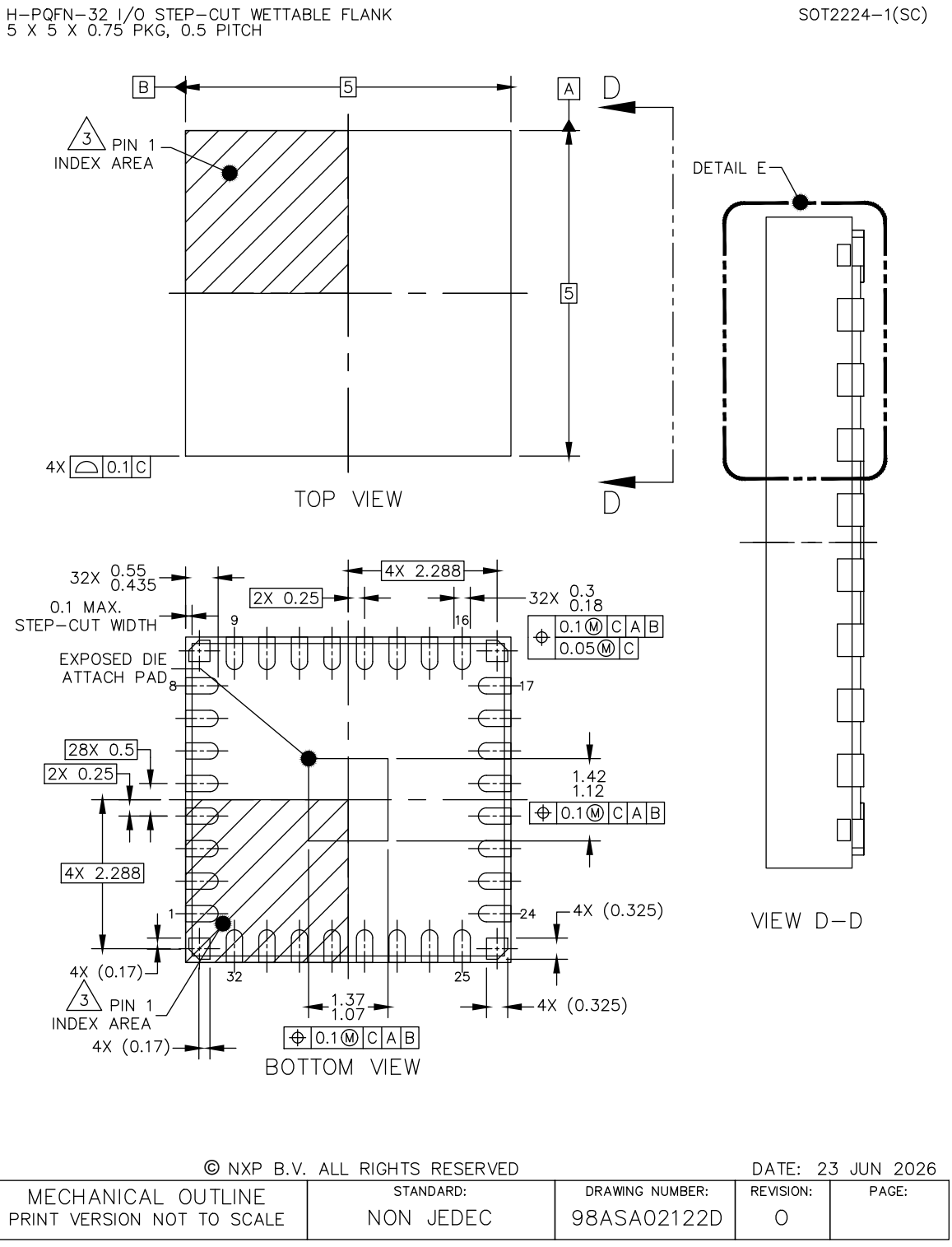


Figure 1. Package outline H-PQFN32 (SOT2224-1(SC))

H-PQFN32, thermal enhanced - plastic quad flat non-lead, 32 terminals, 0.5 mm pitch, 5 mm x 5 mm x 0.75 mm body

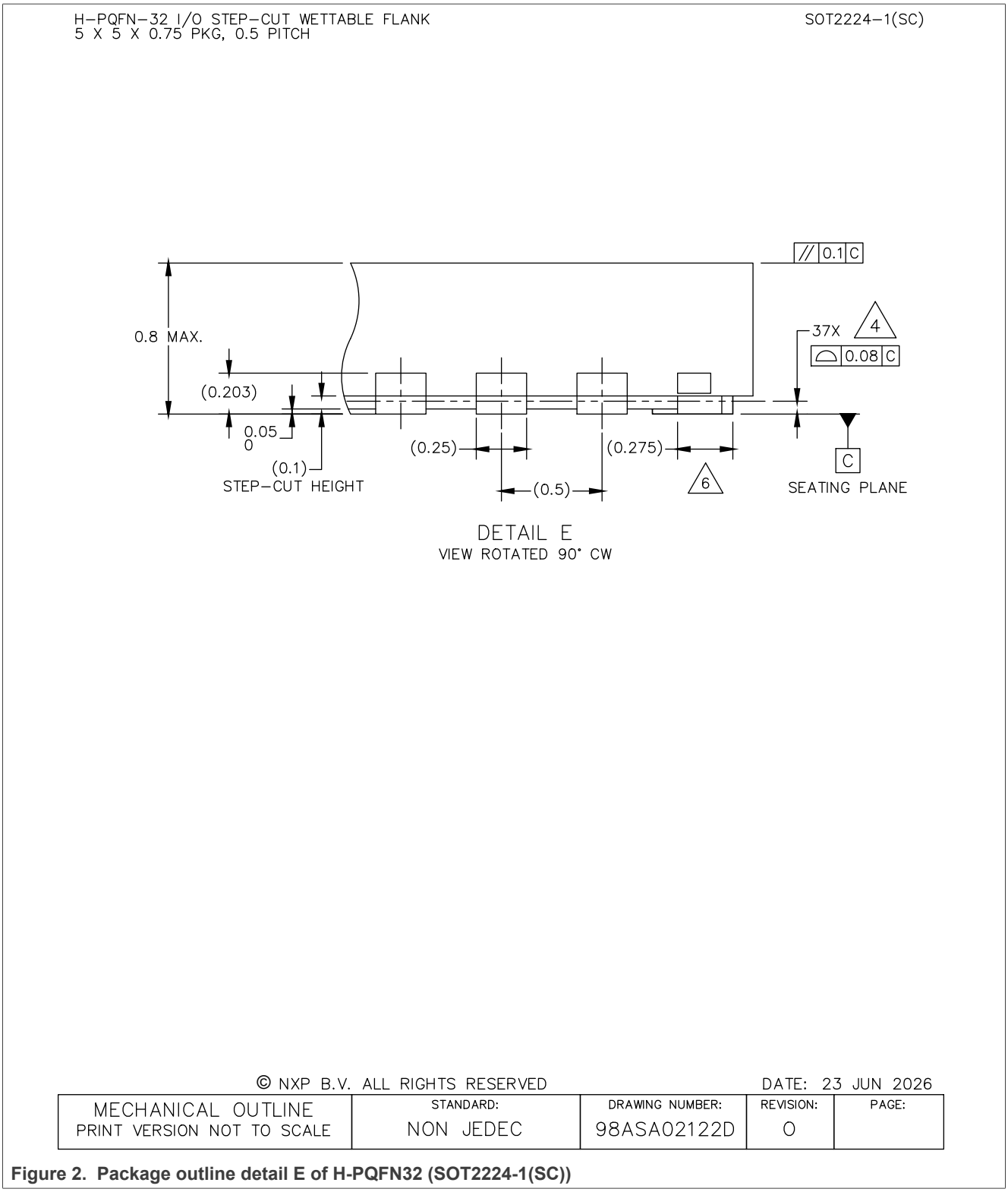
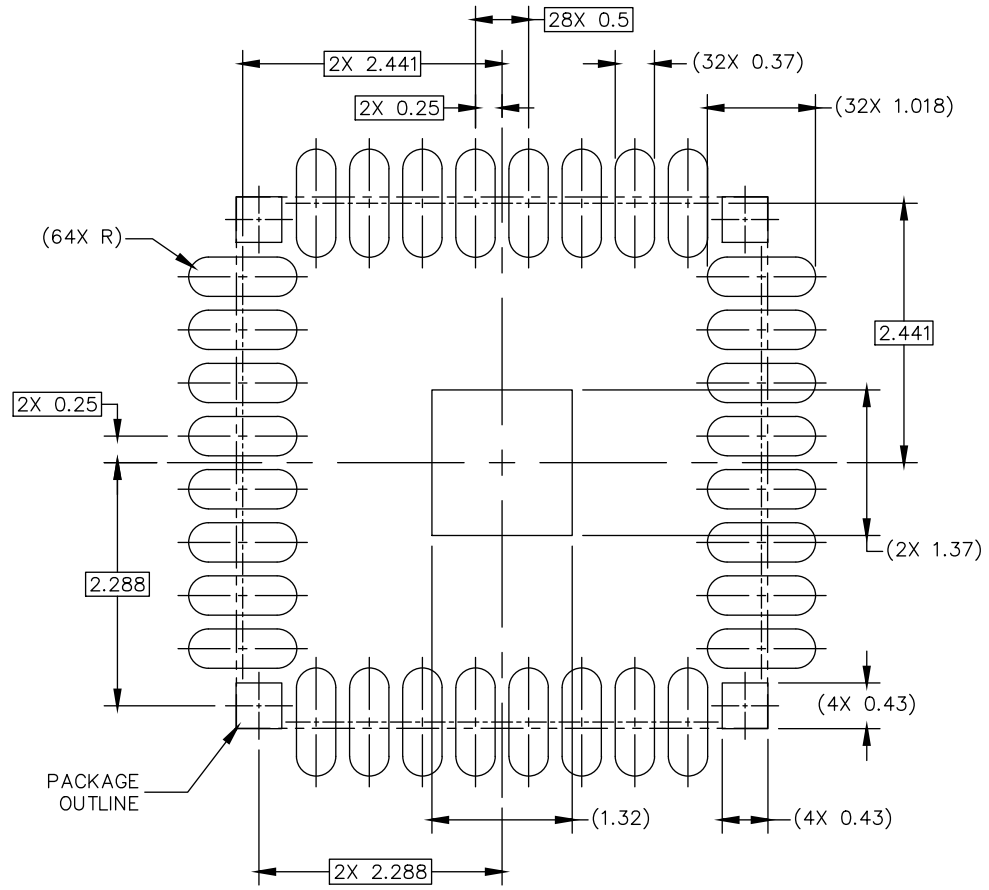


Figure 2. Package outline detail E of H-PQFN32 (SOT2224-1(SC))

3 Soldering



PCB DESIGN GUIDELINES – SOLDER MASK OPENING PATTERN

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

DATE: 23 JUN 2026

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA02122D	REVISION: O	PAGE:

Figure 3. Reflow soldering footprint part1 for H-PQFN32 (SOT2224-1(SC))

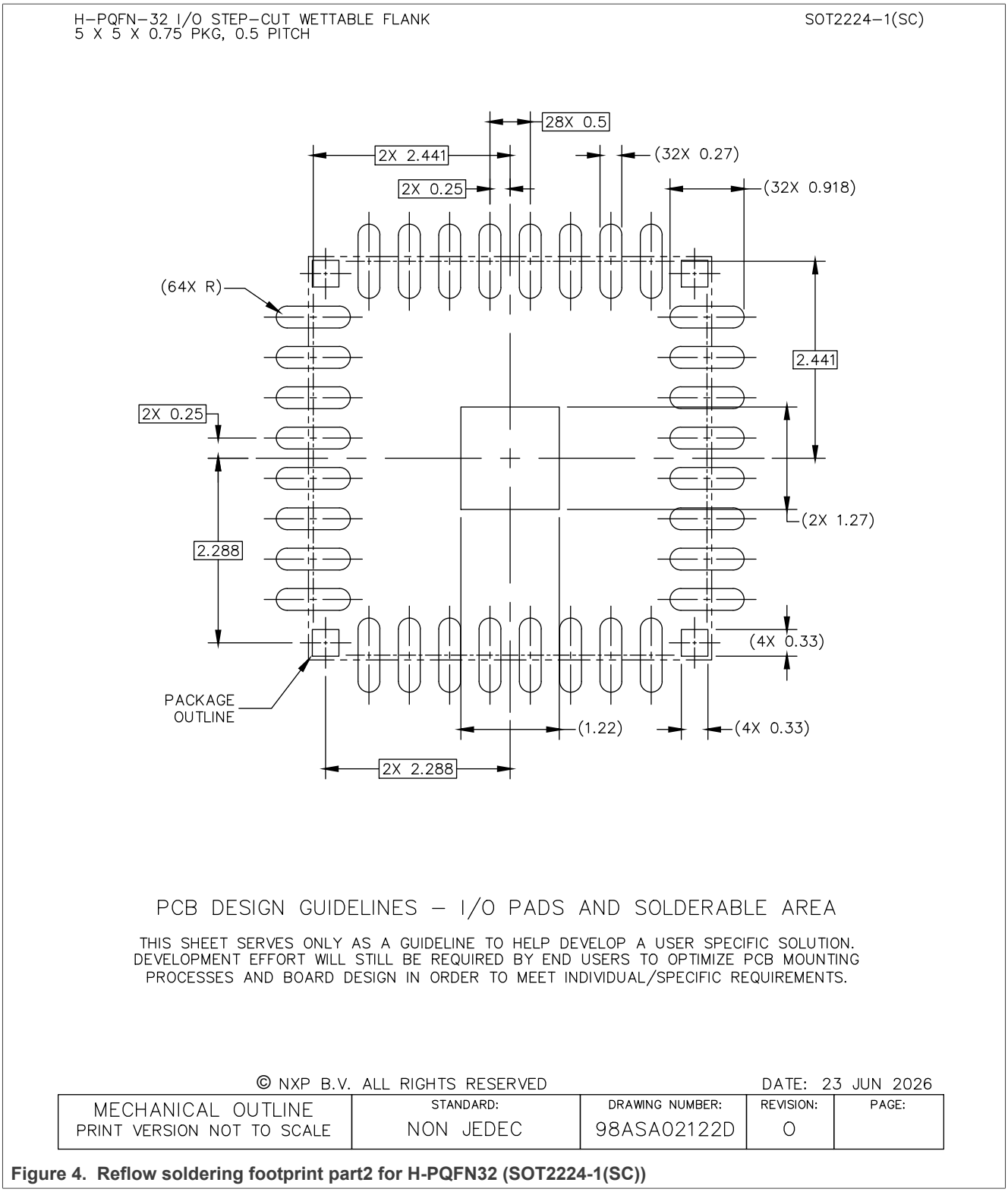


Figure 4. Reflow soldering footprint part2 for H-PQFN32 (SOT2224-1(SC))

H-PQFN32, thermal enhanced - plastic quad flat non-lead, 32 terminals, 0.5 mm pitch, 5 mm x 5 mm x 0.75 mm body

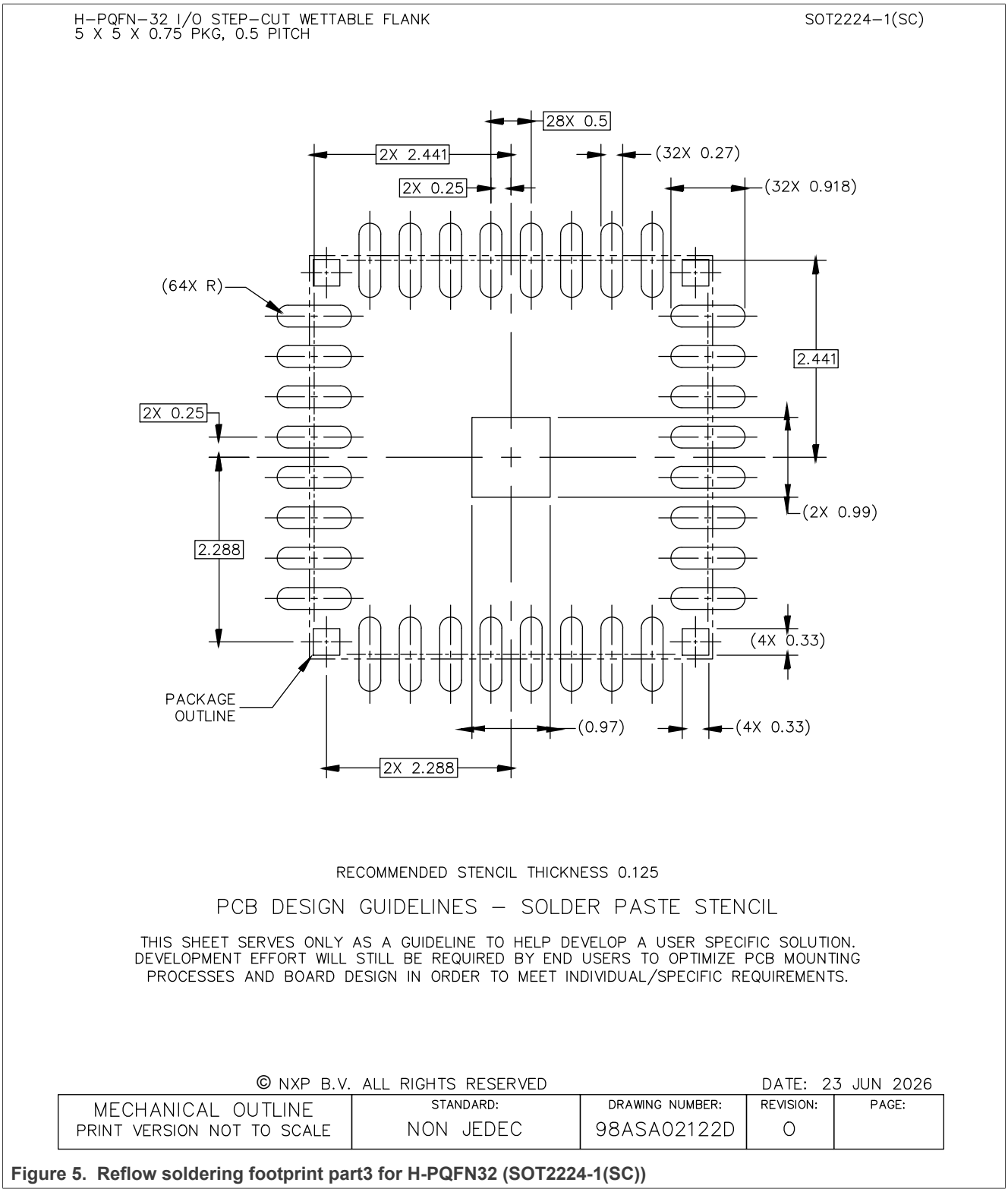


Figure 5. Reflow soldering footprint part3 for H-PQFN32 (SOT2224-1(SC))

H-PQFN32, thermal enhanced - plastic quad flat non-lead, 32 terminals, 0.5 mm pitch, 5 mm x 5 mm x 0.75 mm body

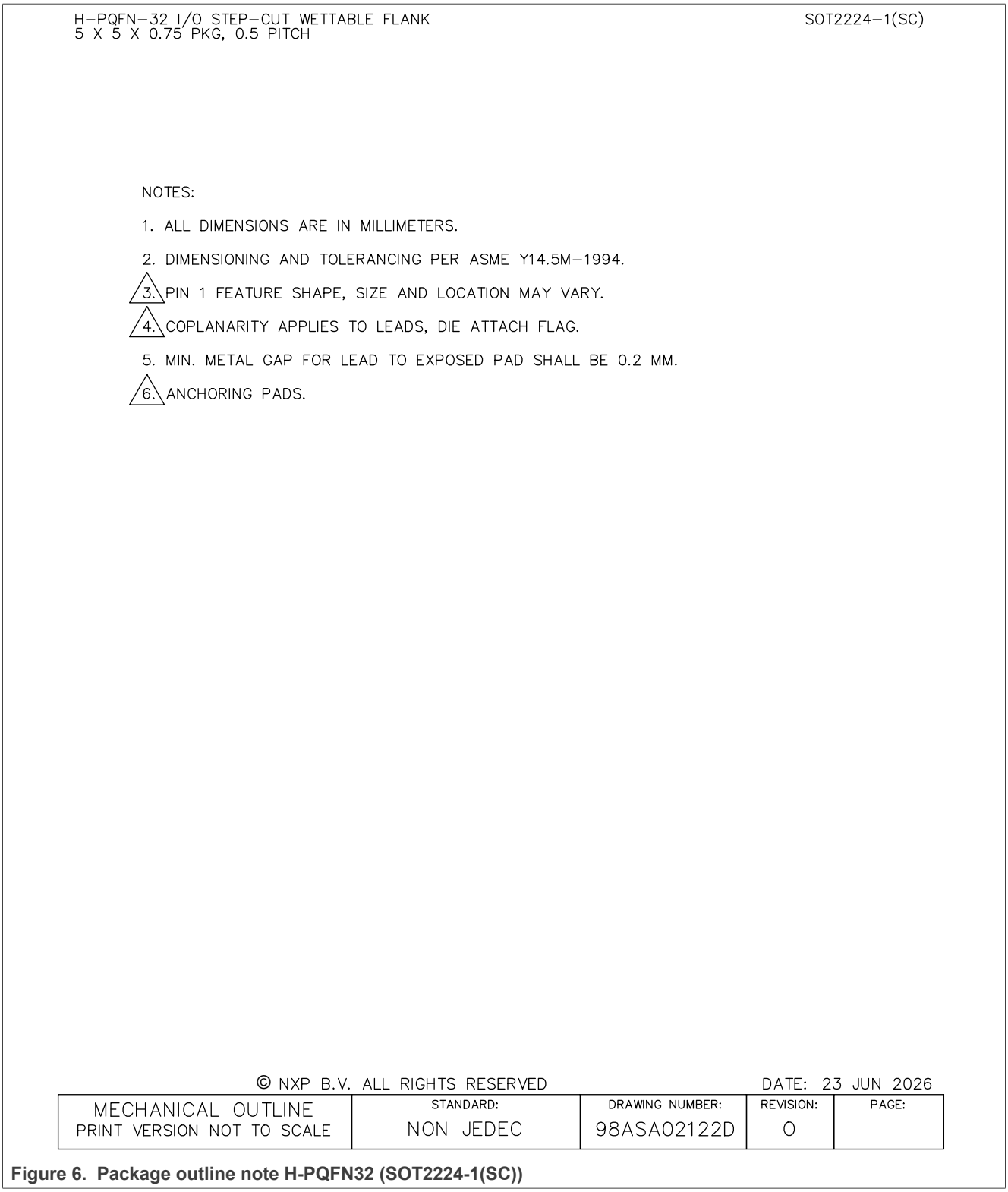


Figure 6. Package outline note H-PQFN32 (SOT2224-1(SC))

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